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Progress on A15 Thin films at Daresbury Laboratory

11th International Workshop on Thin Films and New Ideas for Pushing the Limits of Superconductivity

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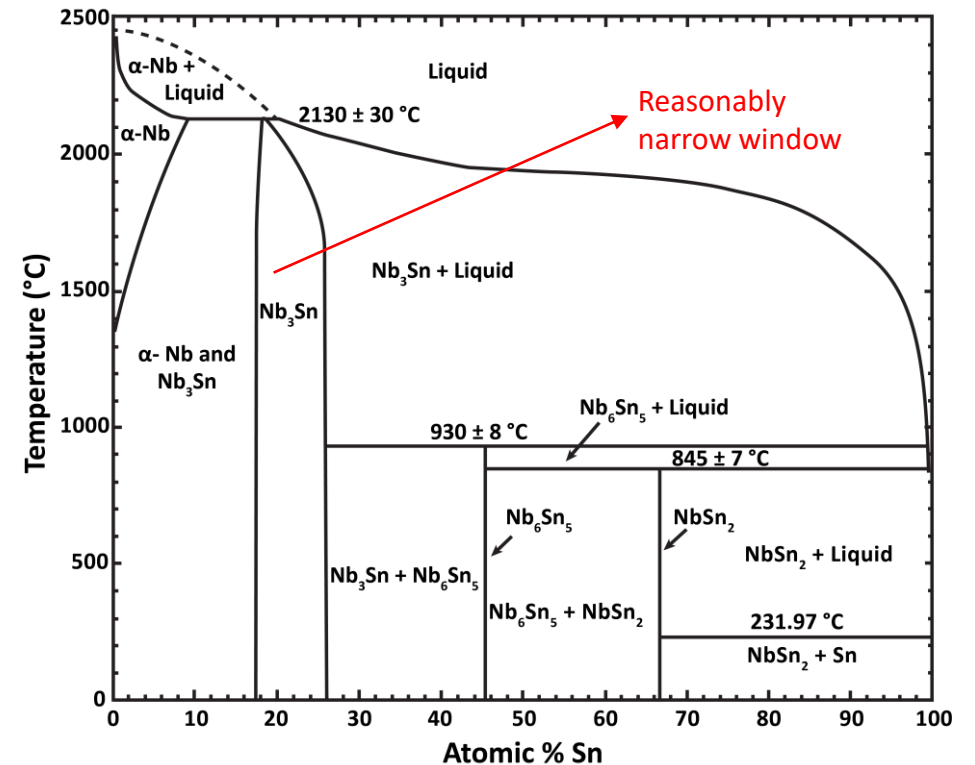
11th International Workshop on Thin Films and New Ideas for
Pushing the Limits of Superconductivity

Motivation

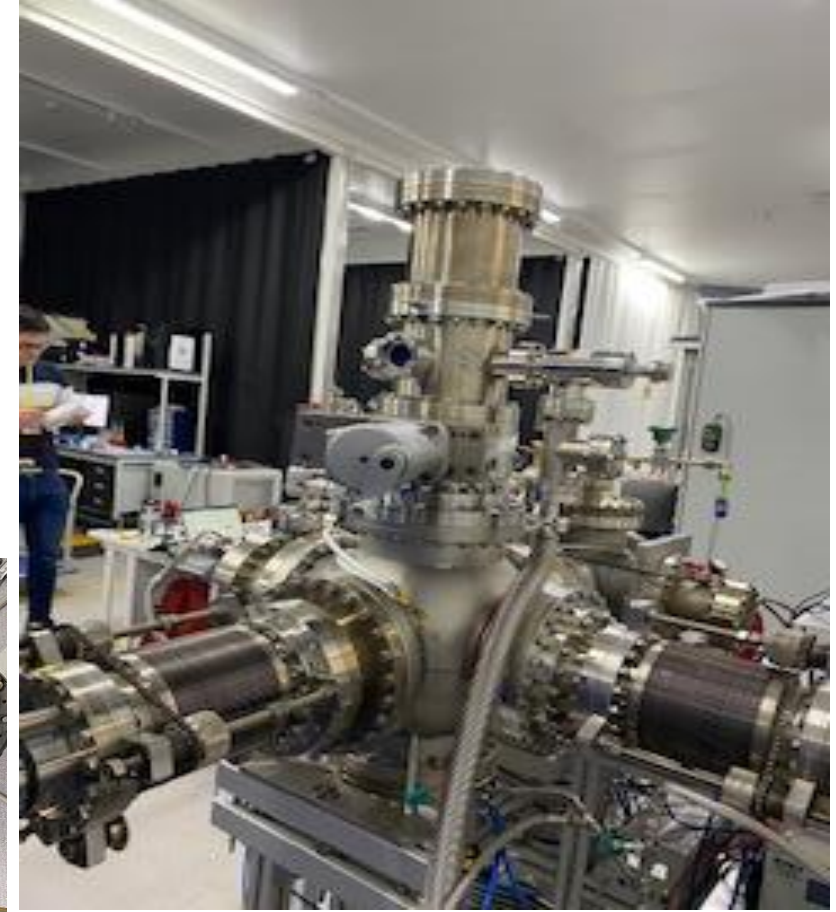
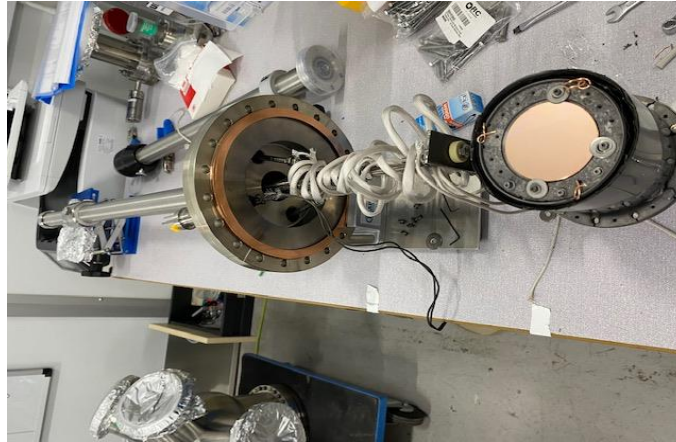
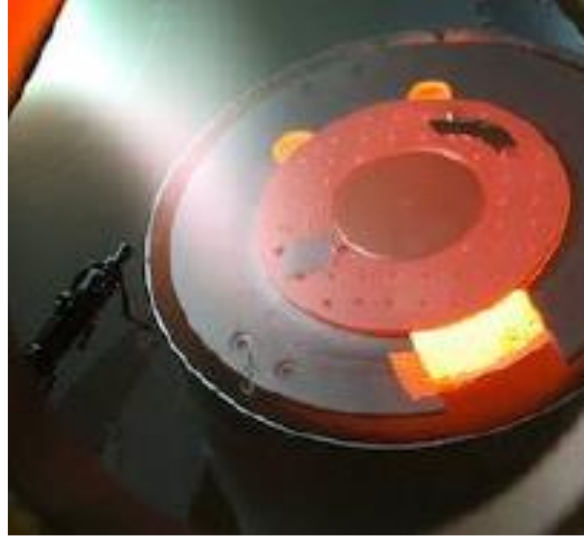
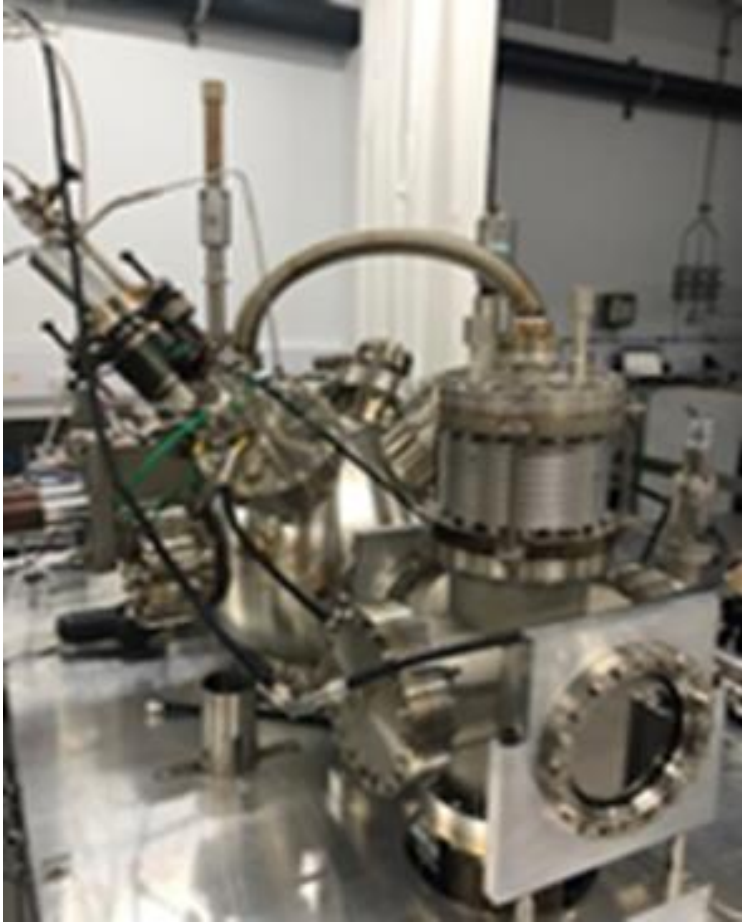
- To optimise deposition parameters to synthesise A15 thin film with optimum SRF properties such as T_c and RF surface Resistance.
 - Optimum Target for optimum stoichiometry
 - Deposition power
 - Deposition temperature
 - Substrate dependence

Target

- Since the stoichiometry for the superconducting phase is reasonably narrow $19 > \text{Sn} < 25 \%$
- For this reason a high purity stoichiometric alloy target was used.
- Deposition parameters was chosen to conserve the instantaneous target stoichiometry.
 - ❑ To reduce Sn evaporation deposition power was set between 50 W to 200 W.
 - ❑ Deposition Temperature set between 550 C to 650 C.
 - ❑ To synthesis thin films with low level of impurity, the residual gas was limited to below 10^{-11} mbar, by baking the system and samples were introduced via a baked load lock.

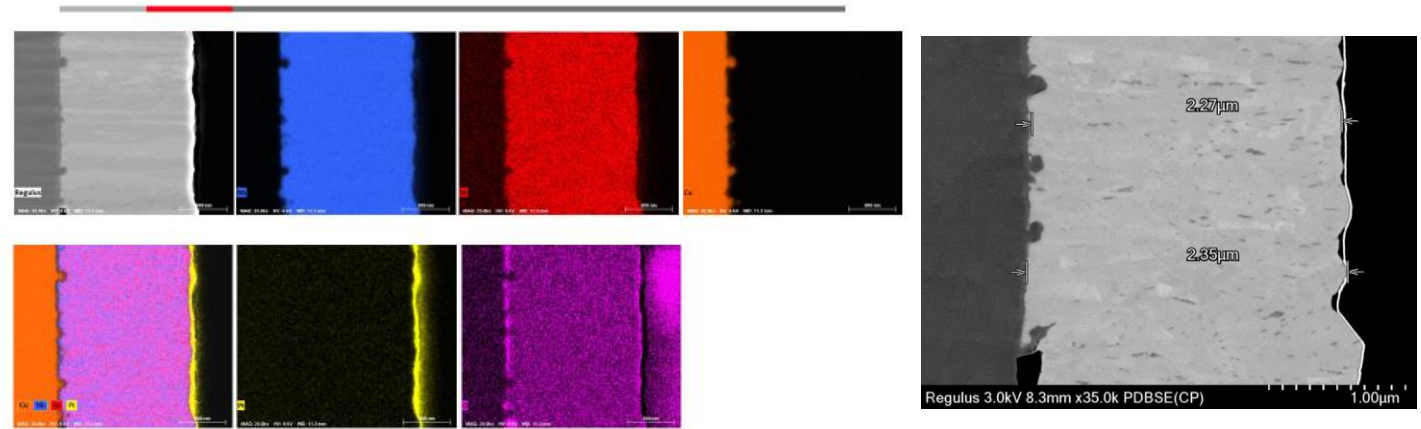


QPR & Planar deposition facility



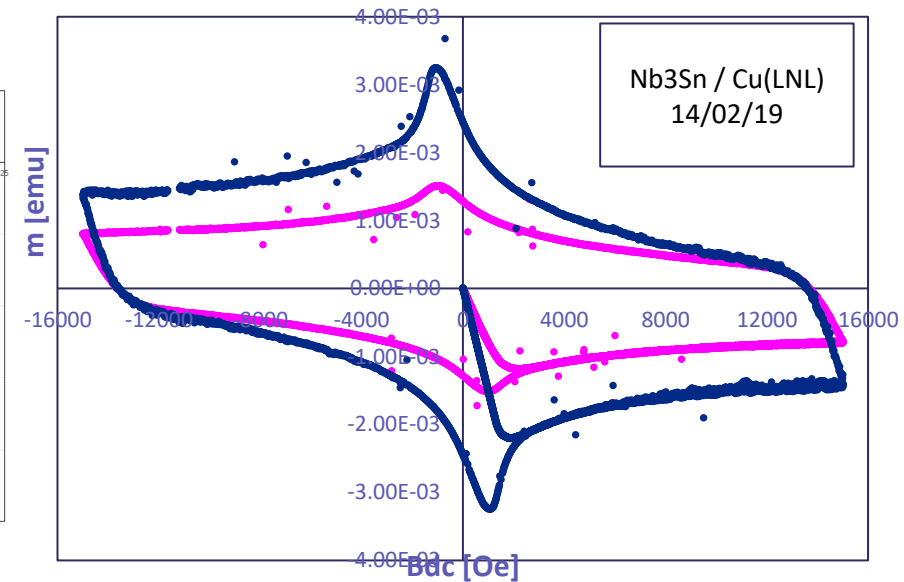
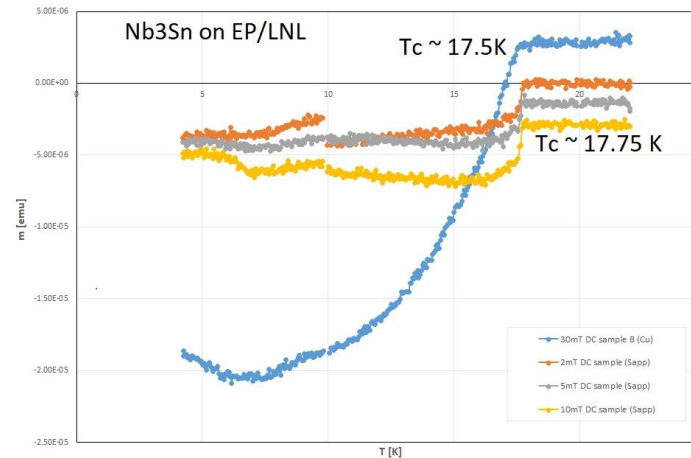
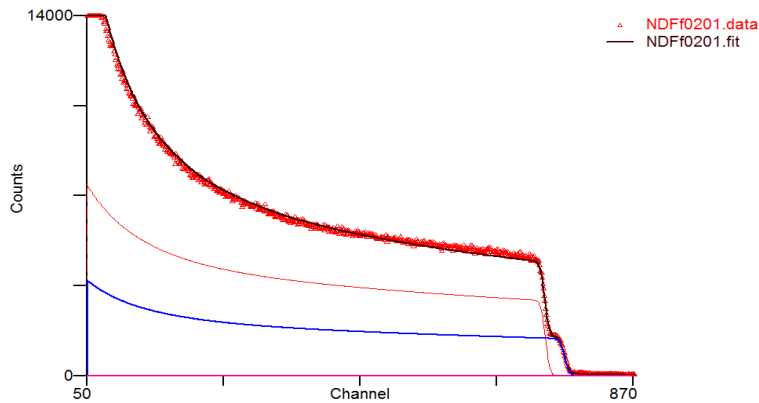
Cu (EP)LNL / Nb₃Sn (single layer) deposited at 650C and 200 W DC

- There are area that seems to be Sn deficient where there are dark contrast spots.
- The T_c was determined to be between 17.75K (on sapphire) and 17.5 on copper
- First Ben is estimated to be 50mT and 140mT deposited on Cu and Sapphire respectively, and H_{C2} above 16 T.
- An interesting results which gives the opportunity of direct deposition of copper cavity rather than Niobium cavity.



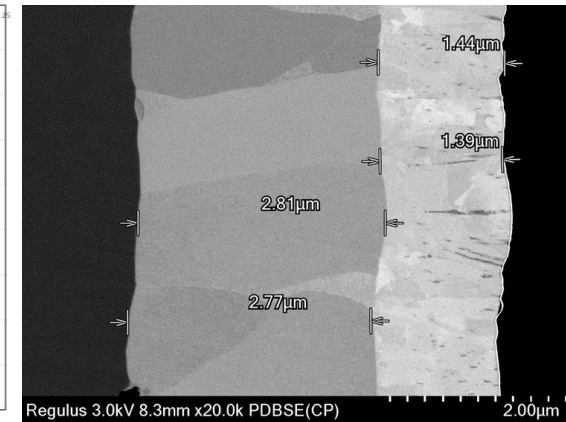
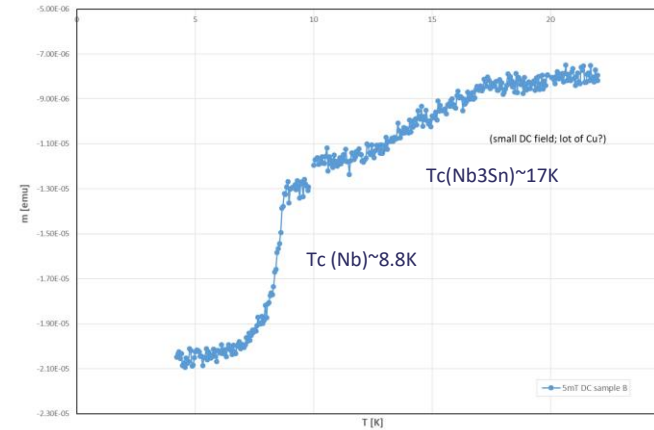
Film thickness of 2.5 Microns

Layer	t (1e15at/cm2)	t (nm)	r(1e22at/cm3)	Nb	Sn	Al	O
1	7606.631	1489.817	5.106	75.0000	25.0000	0.0000	0.0000
2	821647.625	69631.156	11.800	0.0000	0.0000	40.0000	60.0000

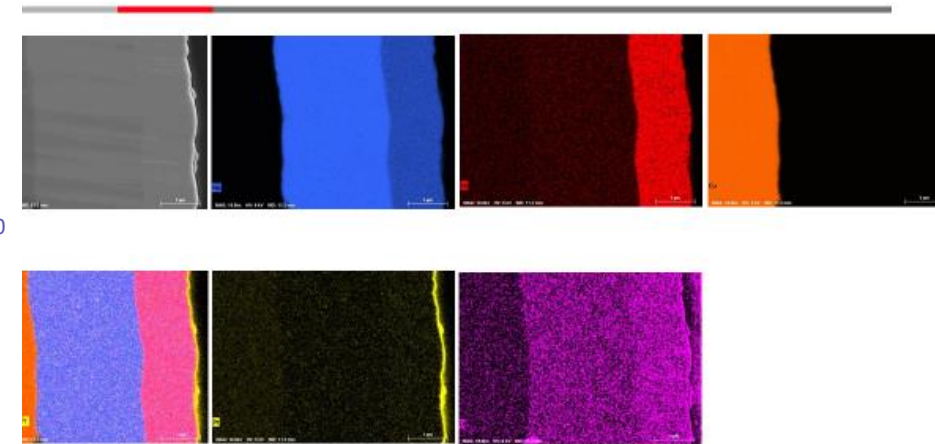
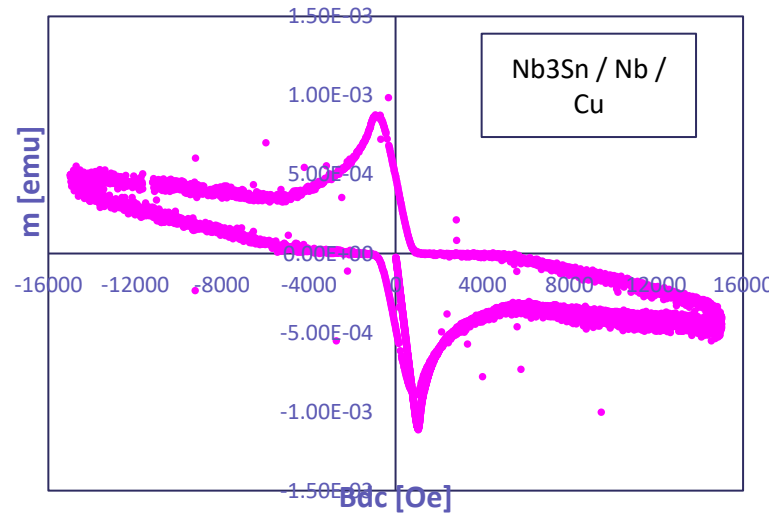
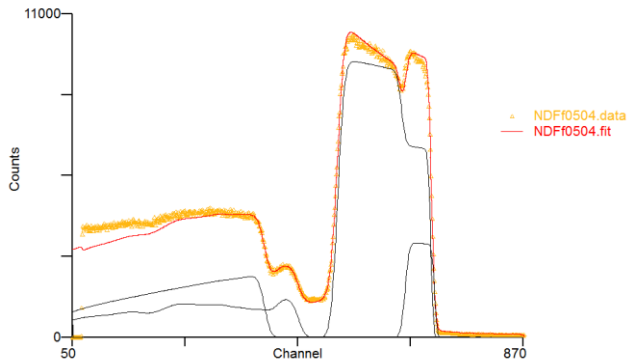


Cu /Nb/Nb₃Sn (double layer) Nb 400W and Nb₃Sn 200W

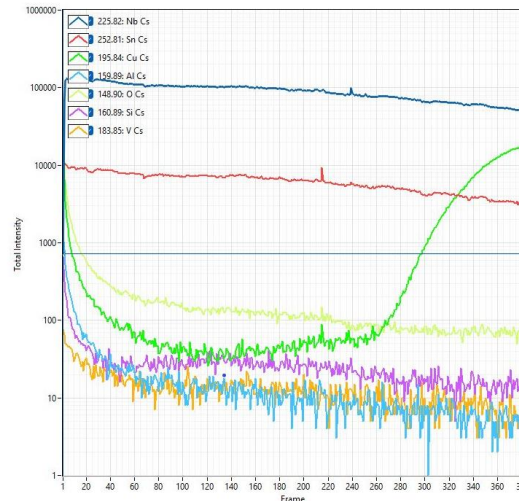
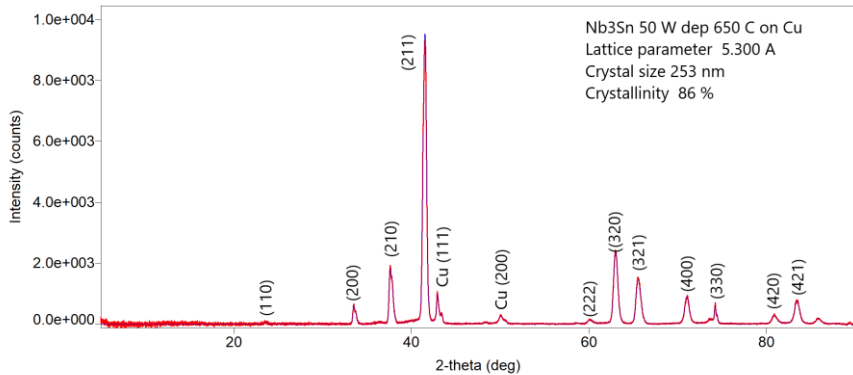
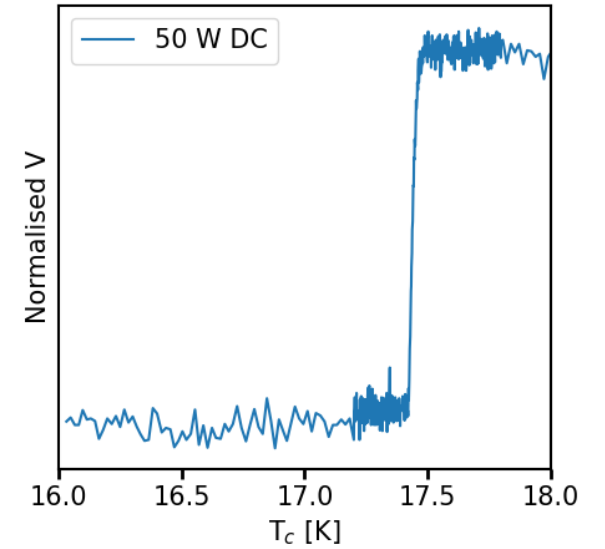
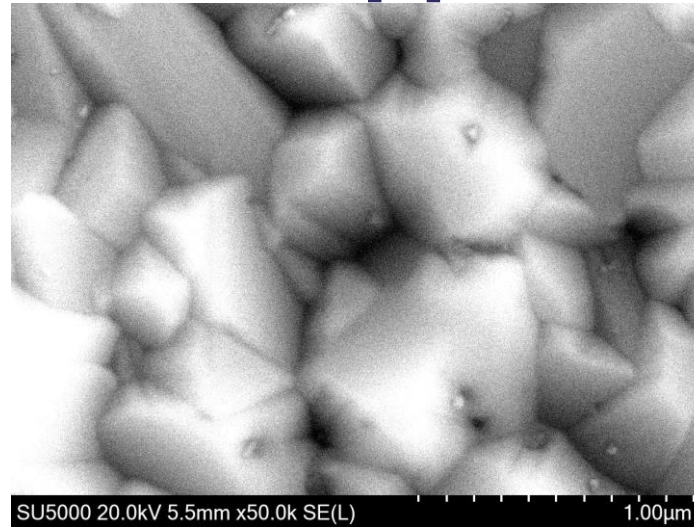
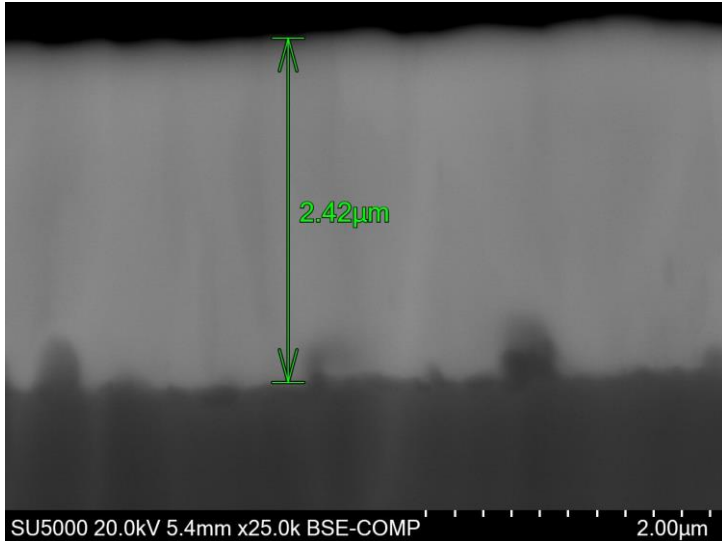
- The interfaces both at Cu/Nb and Nb/Nb₃Sn is well define
- Nb layer is grown in large grain and in a perpendicular direction to the substrate surface
- No intermixing of elements is observed
- However some area of Sn deficiency and rich Sn in Nb₃Sn layer can be observed
- First B_{en} is estimated to be at 95mT.
- RBS analysis shows a uniform film with good stoichiometry which matches the SEM results



Layer	t (1e15at/cm2)	t (nm)	r (1e22at/cm3)	Nb	Sn	O	Al
1	7644.333	1497.201	5.106	75.0000	25.0000	0.0000	0.0000
2	15920.986	2855.270	5.576	100.0000	0.0000	0.0000	0.0000
3	898207.563	76119.281	11.800	0.0000	0.0000	60.0000	40.0000



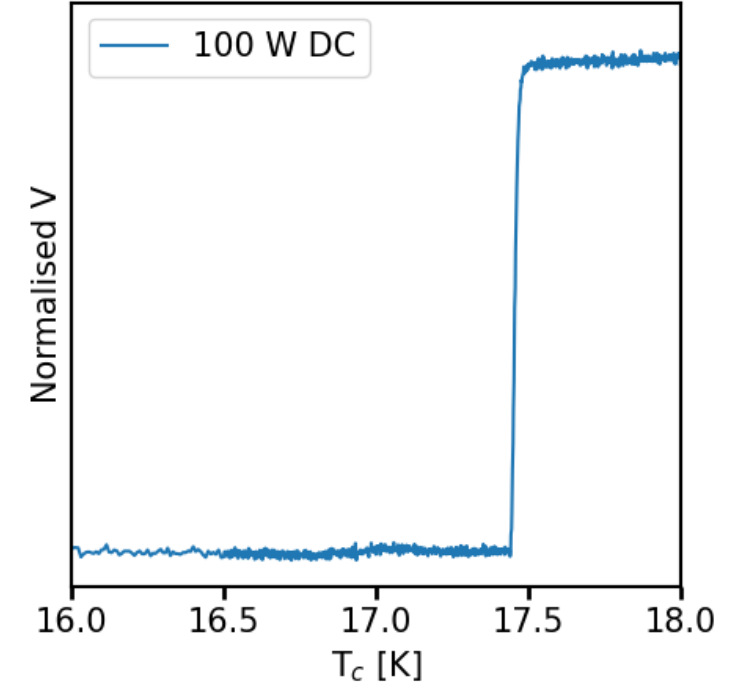
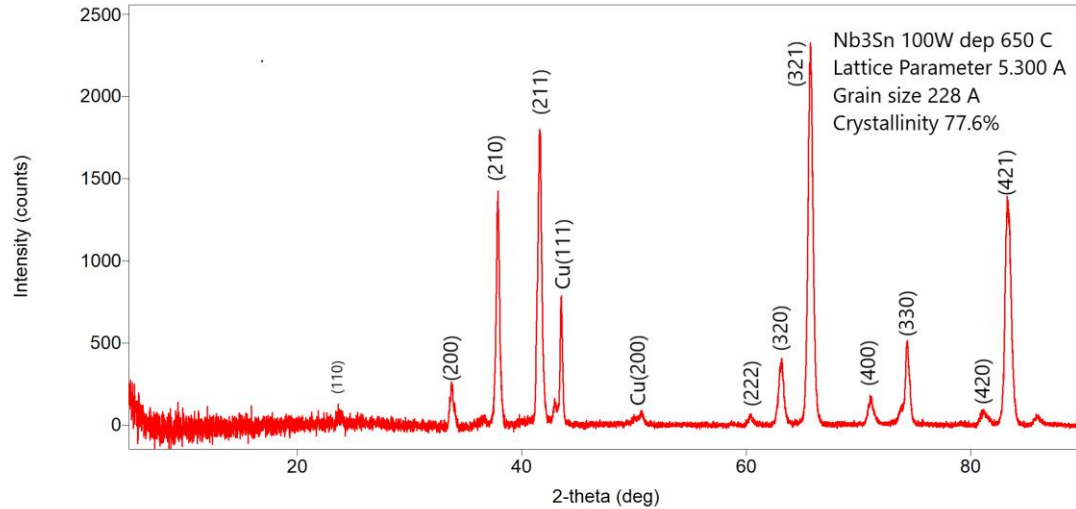
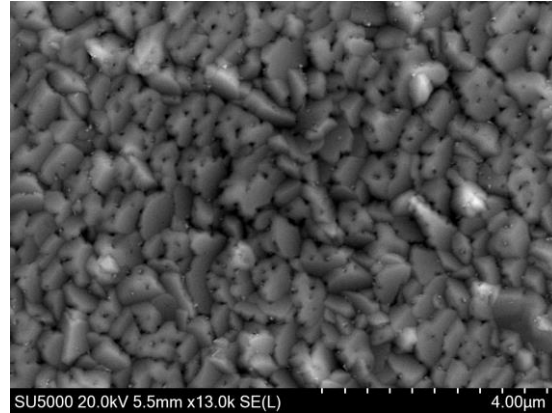
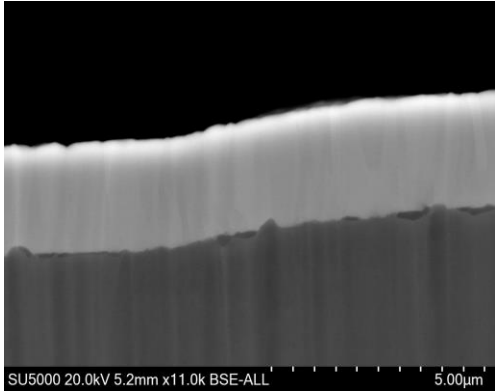
50 W DC Nb₃Sn on 50 & 100 mm diamond turned copper



Cu_24_07_23 50 W T_c = 17
Cu_24_07_23_recentre T_c = 16.1

Sapp_24_07_23 50 W T_c = 17.5
Sapp_24_07_23_recentre T_c = 17.6

100 W DC Nb₃Sn on 50 diamond turned copper

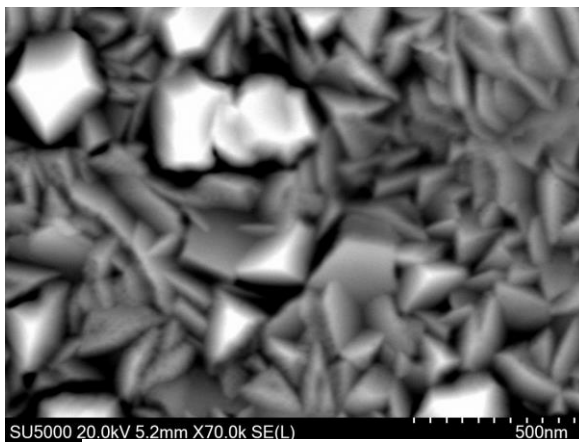
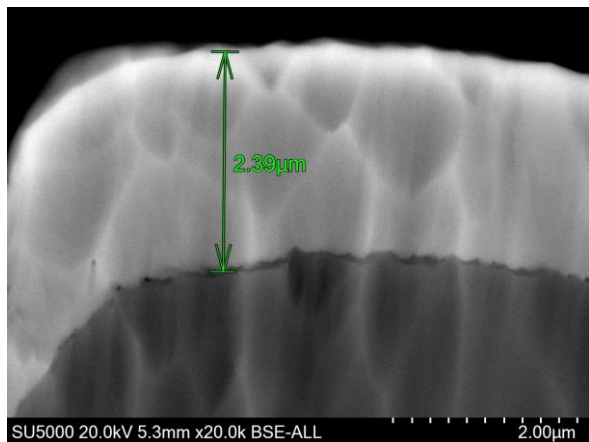


Cu_28_06_23 100W T_c = 17

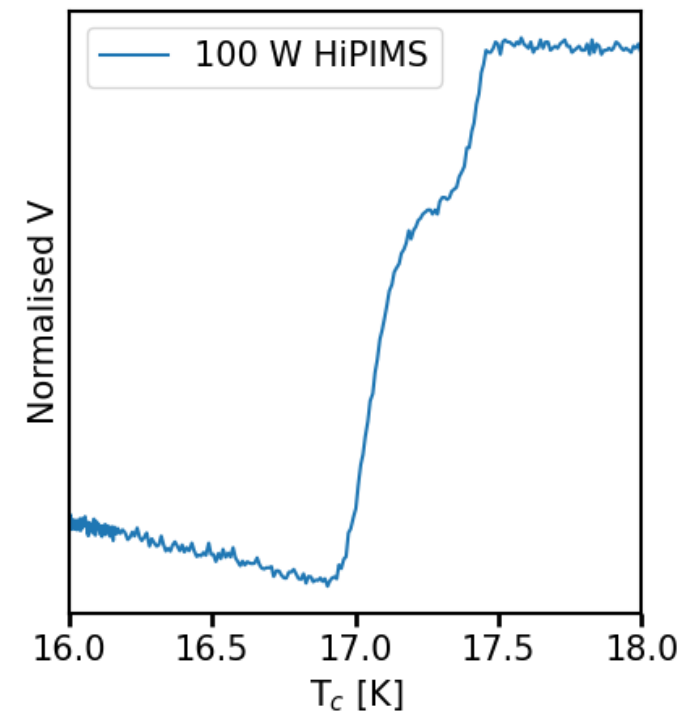
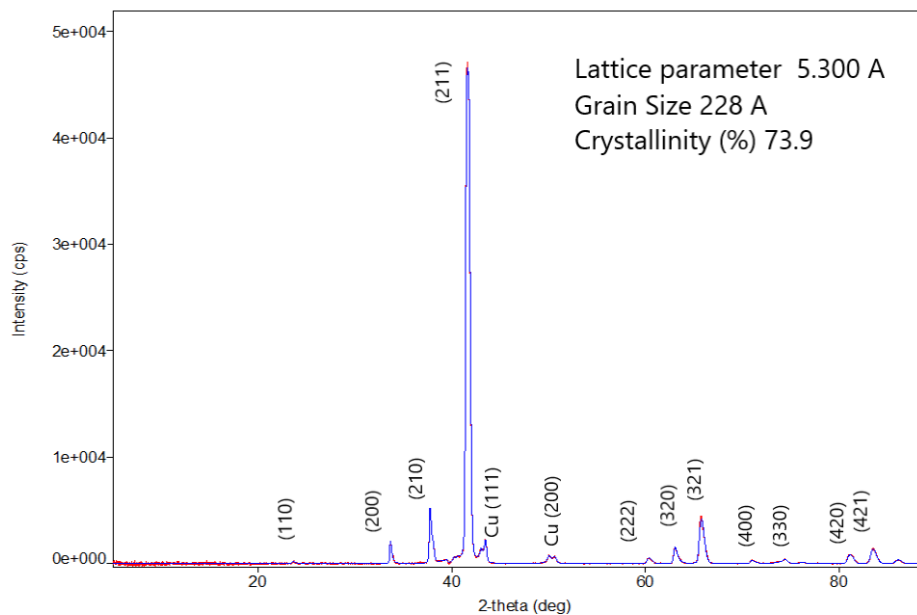
Sapp_28_06_23 100W T_c = 17.5

Sapp_28_06_23_recentre T_c = 17.6

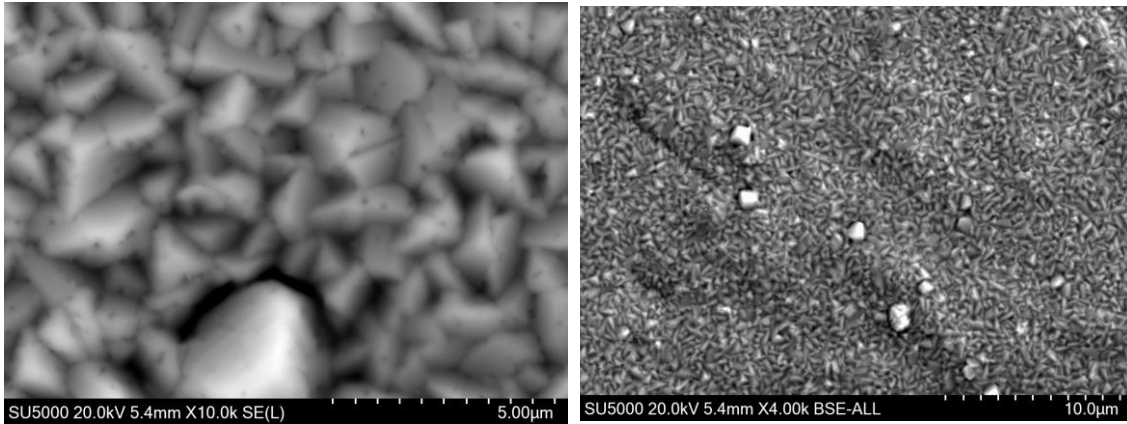
100 W HIPIMS Nb₃Sn on 50 and 100 mm diamond turned copper



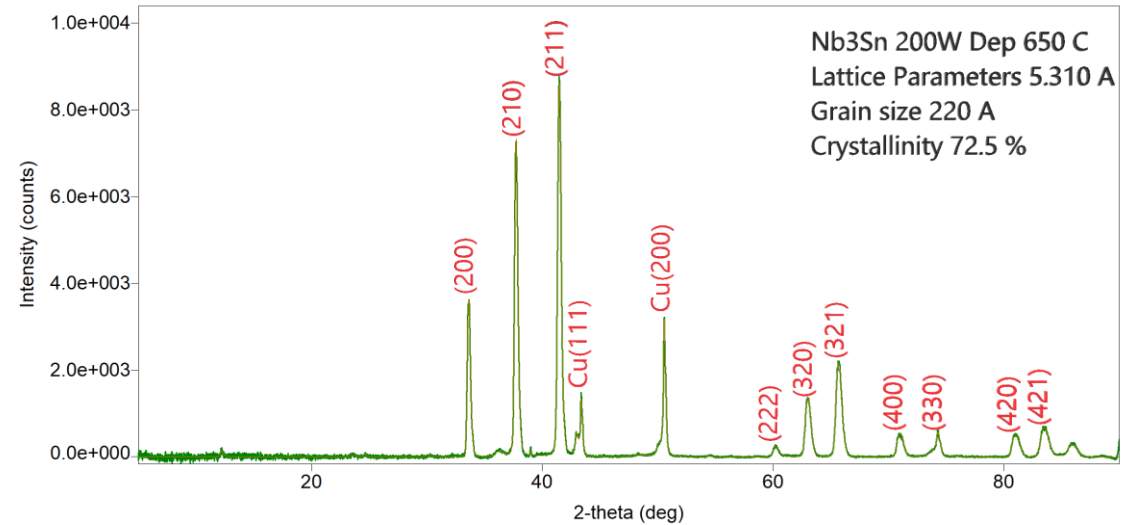
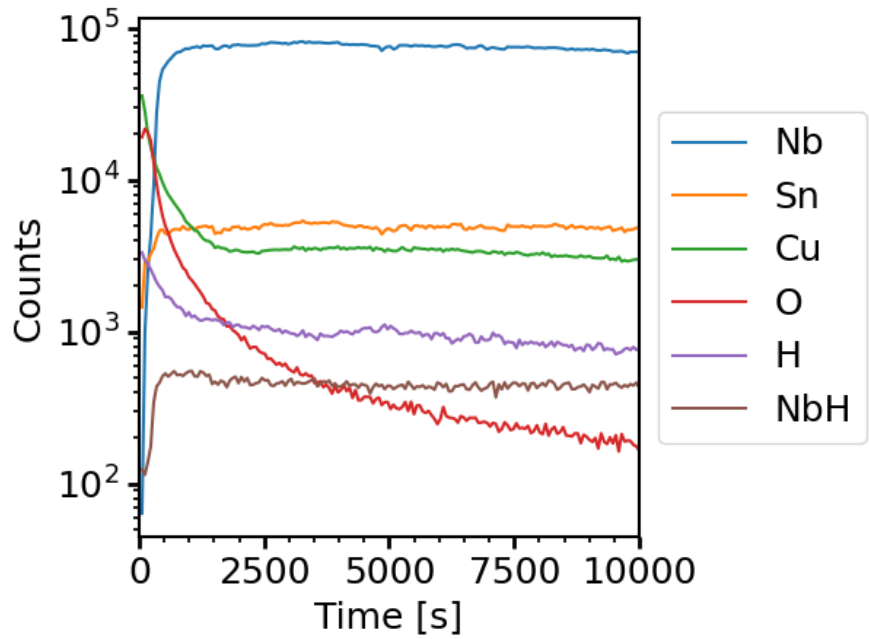
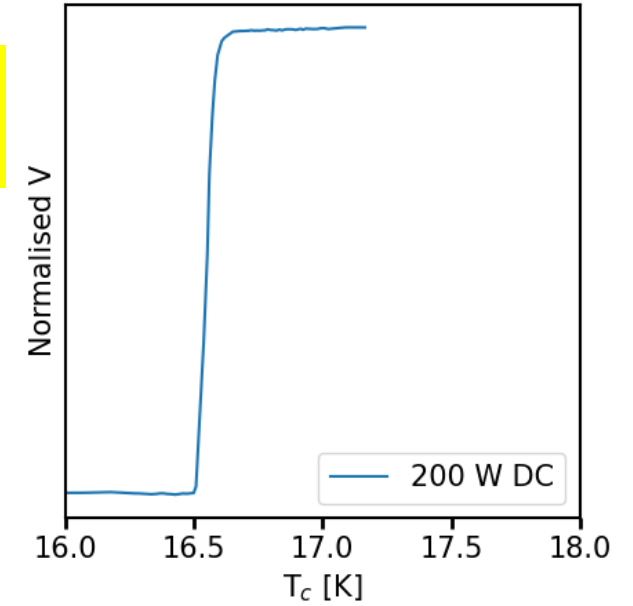
Cu_06_07_23 HiPIMS $T_c = 16.5$
Cu_06_07_23_recentre $T_c = 16.5$



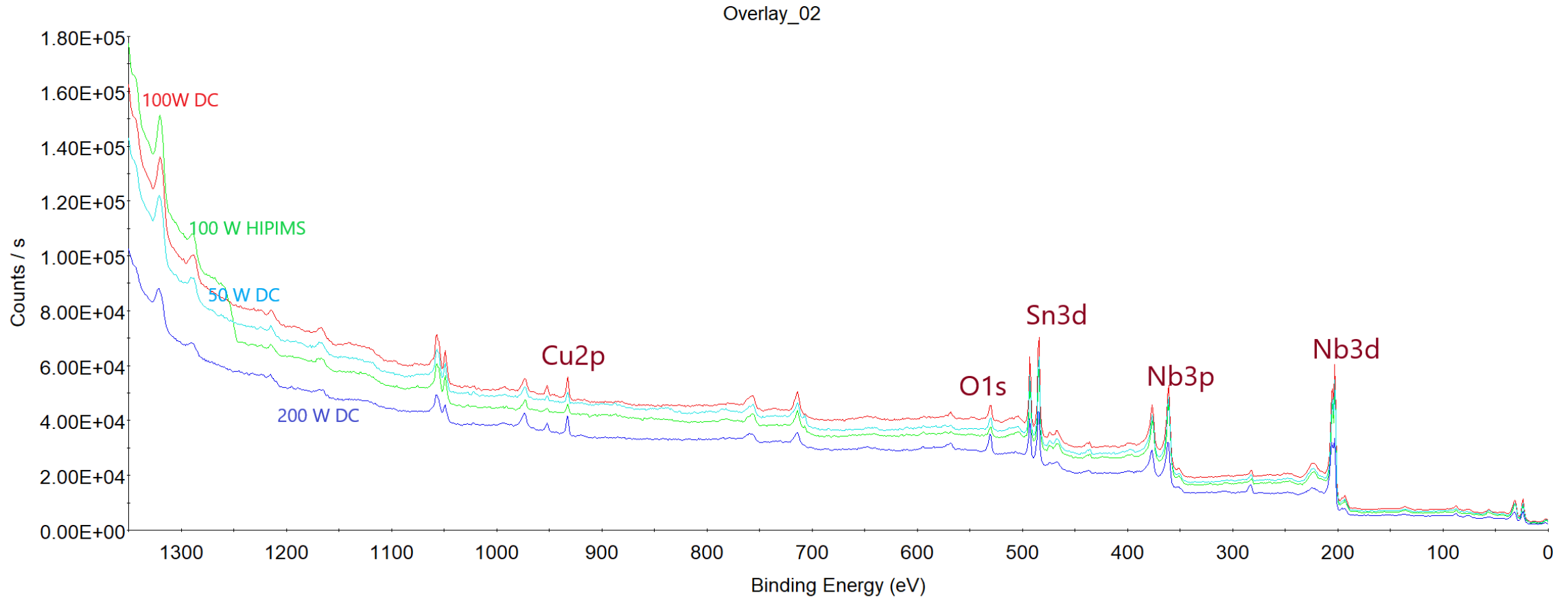
200 W DC Nb₃Sn on 50 & 100 diamond turned copper



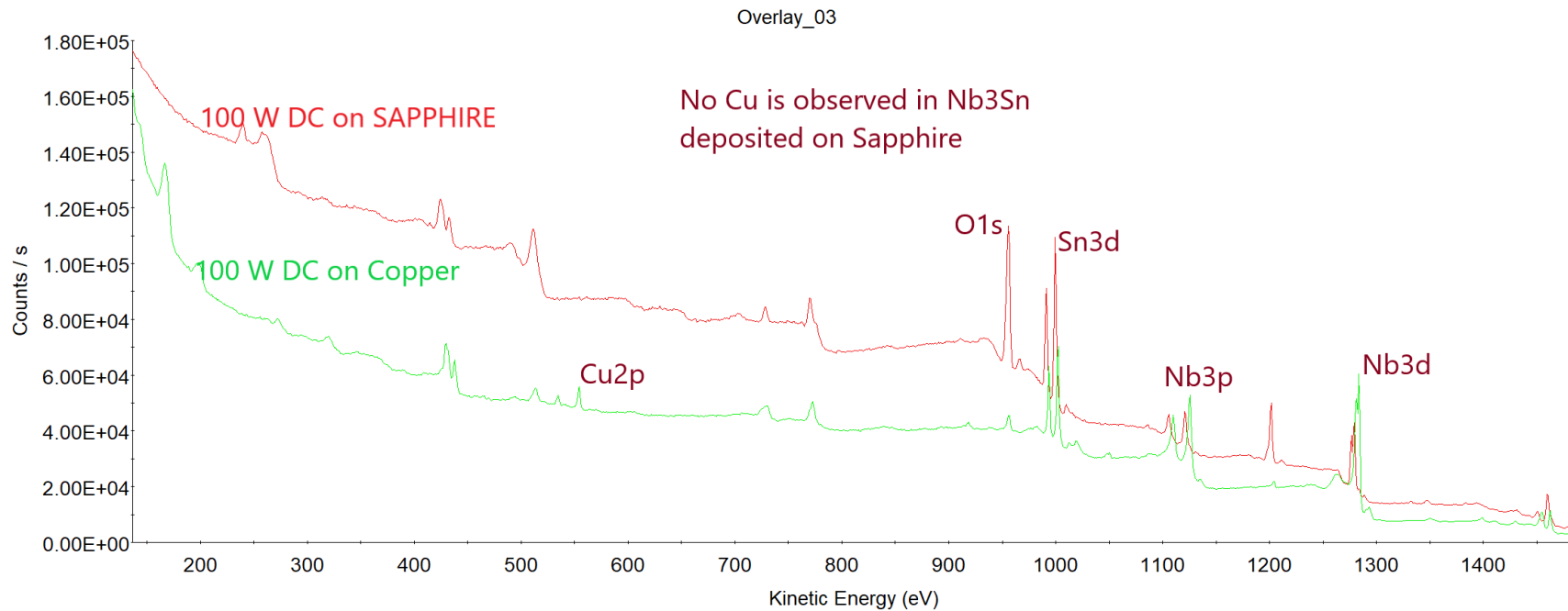
Cu_08_12_22 T_c = 16.8
Cu_08_12_22_recent T_c = 16



XPS analysis of Nb₃Sn on copper



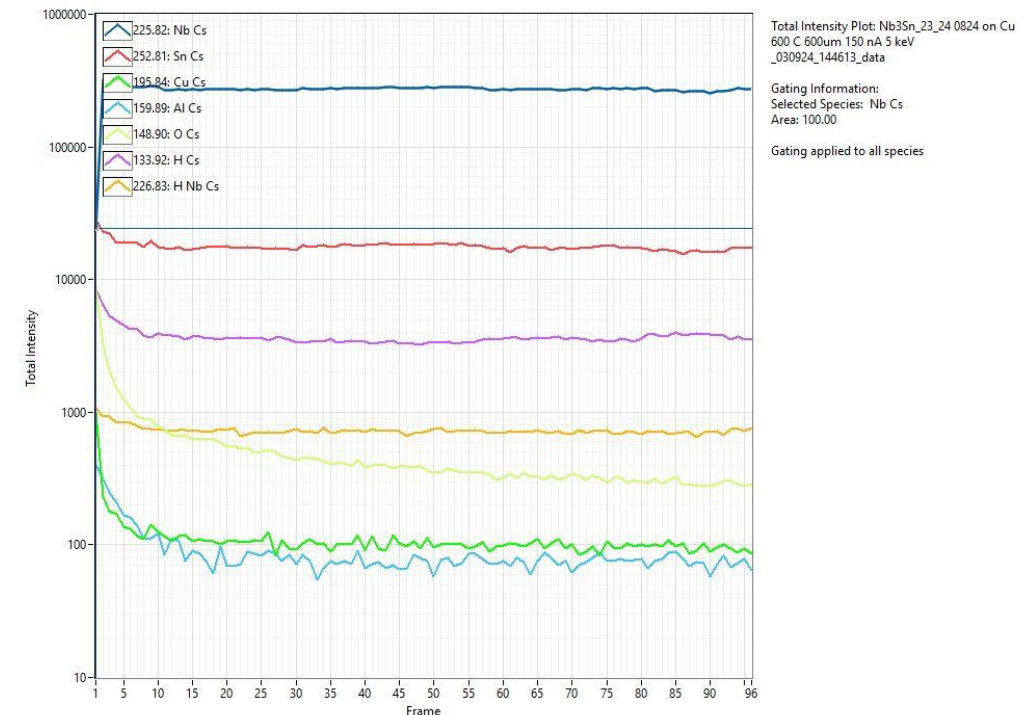
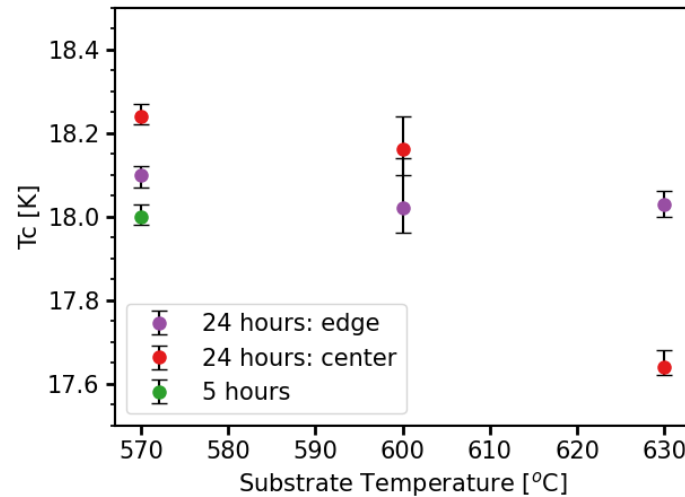
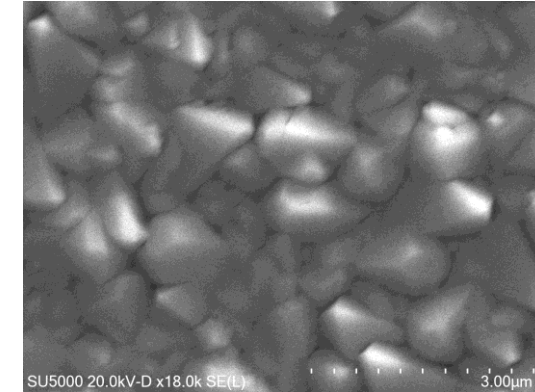
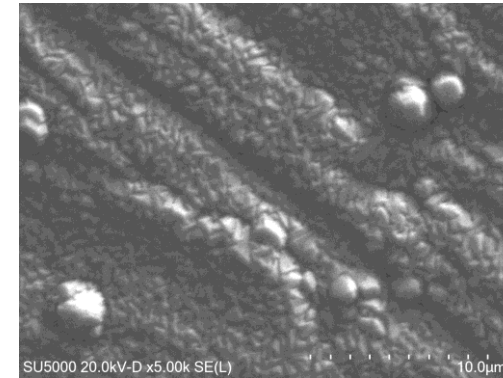
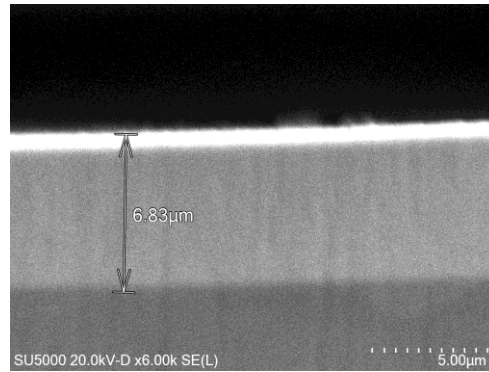
XPS analysis of Nb₃Sn on copper and Sapphire



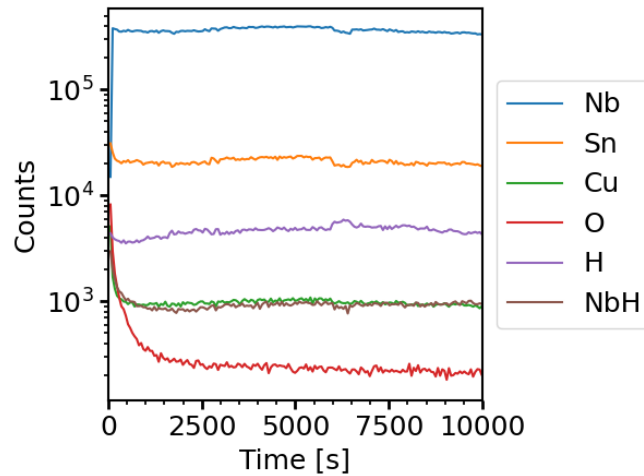
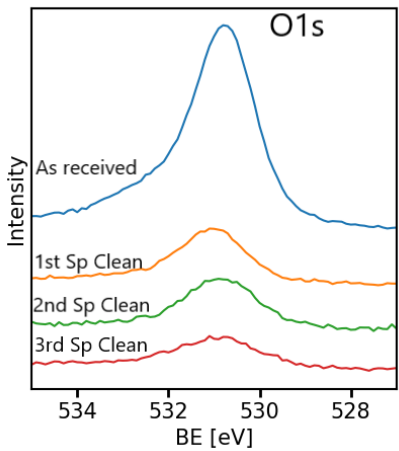
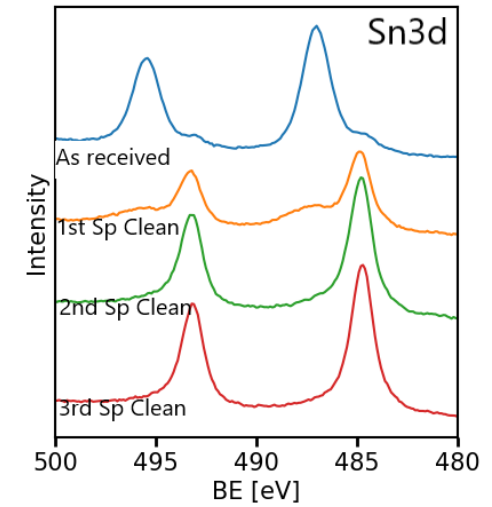
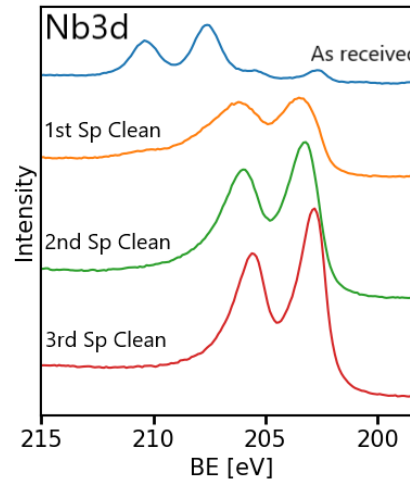
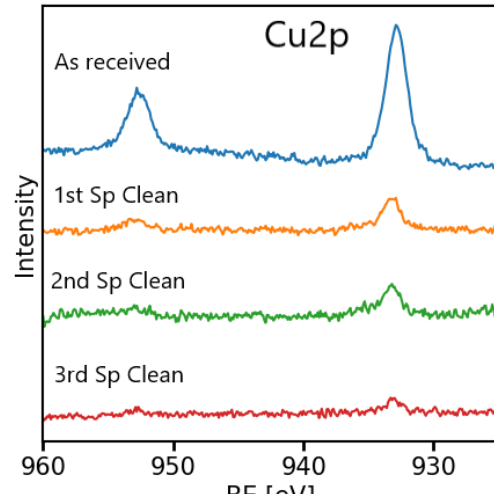
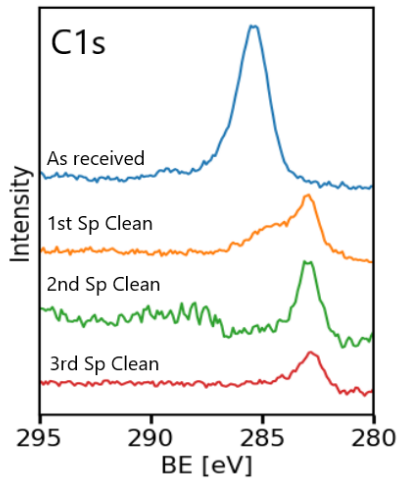
- In both case the surface is dominated with Carbon and Oxygen
- There is no traces of Cu for Nb₃Sn deposited on Sapphire
- Cu can only be seen on Nb₃Sn deposited on copper
- Both Nb and Sn are at oxide state with Nb both in Nb₂O₅ and NbO₂, and Sn in SnO

Deposition Temperature Optimisation

- The deposition power was set at optimum power of 50 W established in power optimisation
- The base pressure was in 5×10^{-10} mbar and at deposition temperature 2×10^{-8} mbar. The deposition pressure was set at 5×10^{-3} mbar and deposition temperature of 570 C to 630 C.
- The optimum T_c of 18.26 K for Nb3Sn deposited on Sapphire at 570 C.
- Thinner film gave a T_c of 18 K.
- Increasing the deposition range reduces the T_c to 18.1 K and 17.6 K for dep temperature of 600C and 630C respectively.



XPS analysis of Nb₃Sn on Cu at 570C



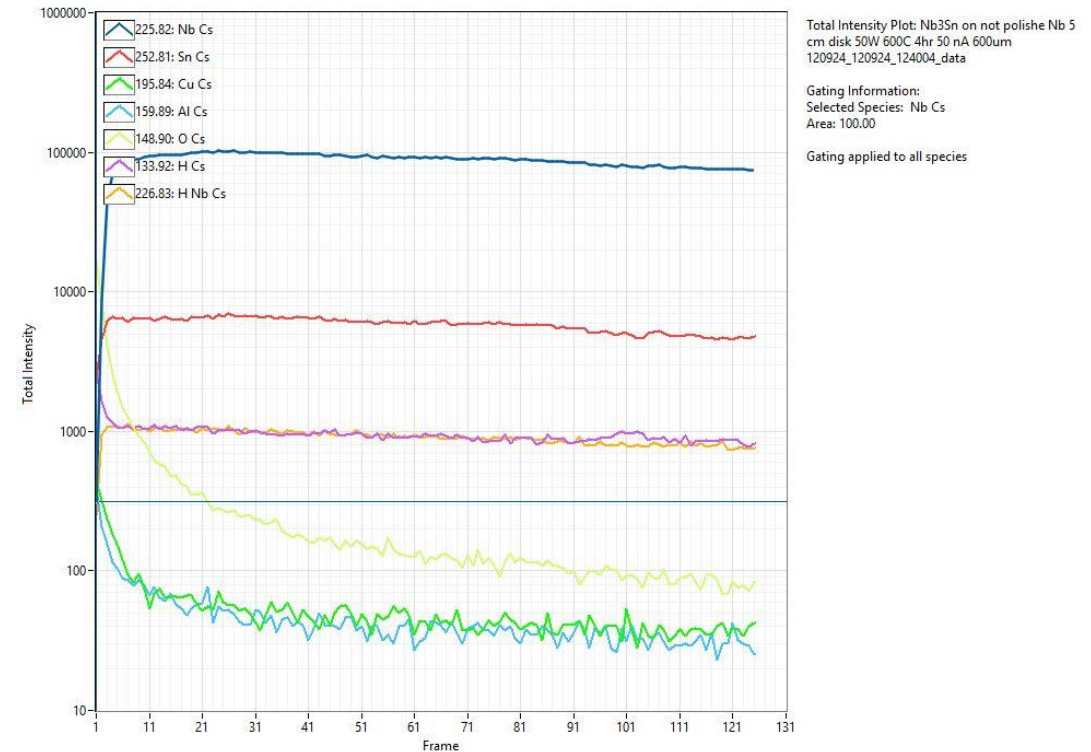
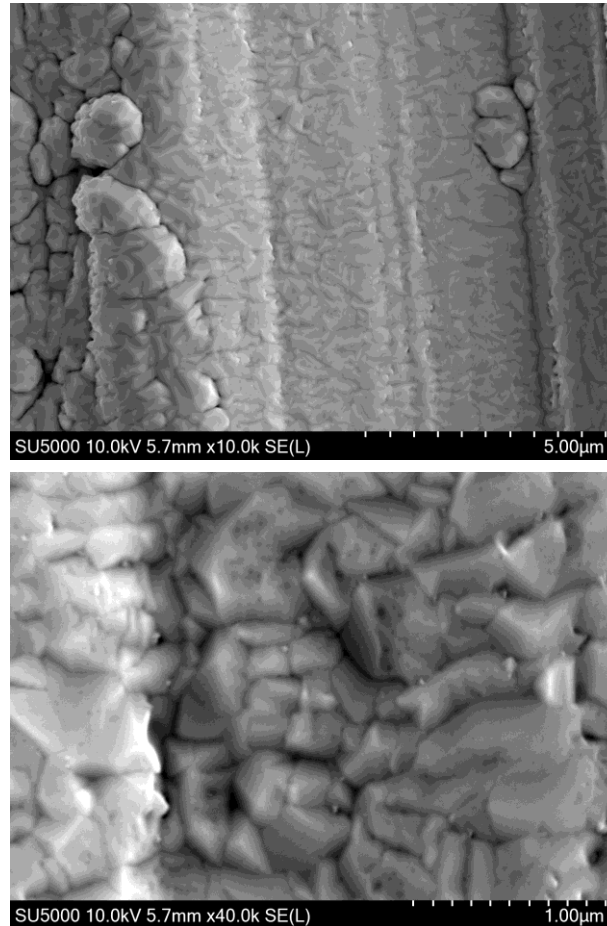
	As received	As received	1 st Sput clean	1 st Sput clean	2 nd Sput clean	2 nd Sput clean	3 rd Sput clean	3 rd Sput clean
Nb	47.74	6.09	65.61	13.6	75.05	22.23	75.92	22.47
Sn	52.26	3.22	34.39	7.14	24.95	7.39	24.06	7.12
Cu		2.61		1.69		1.41		1.2
O		37.16		46.33		23.71		25.55
C		49.92		31.23		22.63		21.83
H		?		?		?		?

As seen in SIMS depth profile the surface is dominated by oxygen, carbon as well as being Sn rich and presence of Cu on the surface.

Both Nb and Sn are in oxide state of Nb₂O₅ and SnO respectively.

Nb₃Sn deposited on Nb at 50 W and 650C

- The grain are much larger in comparison with films deposited on Cu and sapphire.
- T_c of 16 K was determined by penetration method.
- SIMS analyses showed the highest impurity present in the Nb₃Sn is hydrogen
- More analysis of being done to stablish the low T_c as compared to both Cu and sapphire.



Synthesis of V₃Si

Motivation and Difficulties

V₃Si is a potential candidate for SRF thin films with similar superconducting parameters as other A15 Materials.

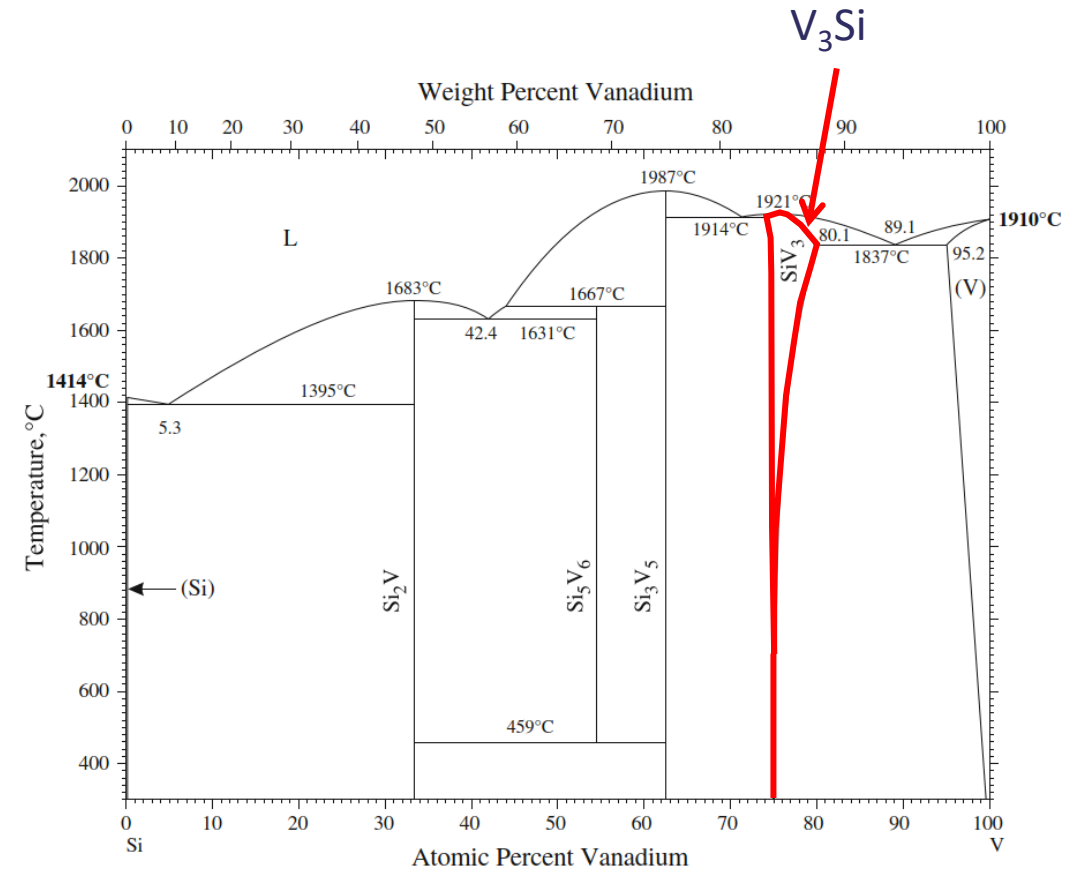
However, there are some difficulties:

- Stoichiometry control is very narrow window.
- Impurities can drastically affect T_c.
- Vanadium has a relatively high diffusivity when considering typical cavity substrates (Nb, Cu).

Table 1. Superconducting parameters for some candidate materials considered for SRF applications.

Material	T _c (K)	ρ _n (μΩ cm)	H _c (0) (T)	H _{c1} (0) (T)	H _{c2} (0) (T)	λ (nm)	Δ (meV)	ξ (nm)
Nb	9.23	2	0.2	0.18	0.28	40	1.5	35
NbN	16.2	70	0.23	0.02	15	200–350	2.6	3–5
NbTiN	17.3	35		0.03	15	150–200	2.8	5
Nb ₃ Sn	18	8–20	0.54	0.05	28	80–100	3.1	4
V ₃ Si	17	4	0.72	0.072	24.5	179	2.5	3.5
Nb ₃ Al	18.7	54			33	210	3	
Mo ₃ Re	15	10–30	0.43	0.03	3.5	140		
MgB ₂	40	0.1–10	0.43	0.03	3.5–60	140	2.3 / 7.2	5
Pnictides	30–55		0.5–0.9	30	50–135	200	10–20	2

A15 materials



V-Si binary phase diagram [1]



Table from: Anne-Marie Valente-Feliciano 2016 *Supercond. Sci. Technol.* **29** 113002

[1] Okamoto, H. (2010) 10.1007/s11669-010-9733-5

V₃Si Deposition System

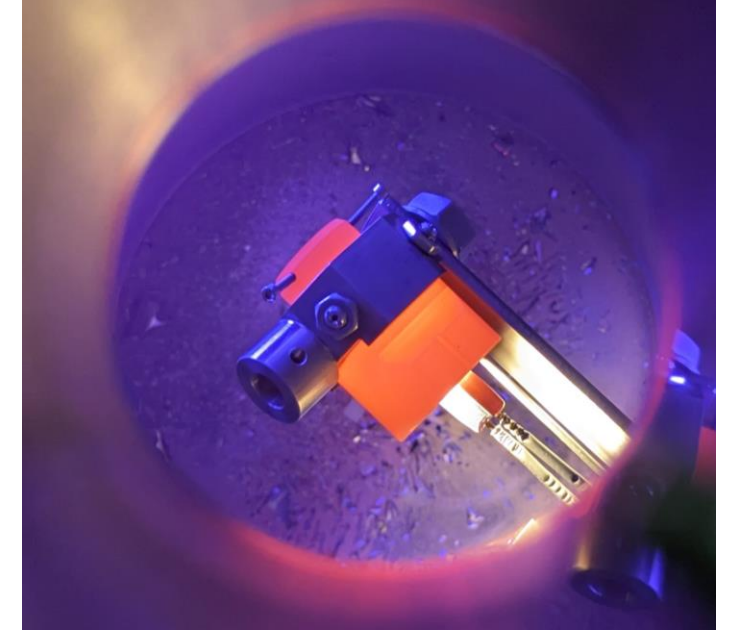
- Deposition system has a load lock to maintain a clean V₃Si target with a base pressure $<4 \times 10^{-9}$ mbar.
- Sample stage reaches a max temperature of ~ 850 °C and can be biased during deposition.
- All samples were deposited using a single V_{75%}Si_{25%} alloy target.
- Kr gas was used as the process gas.

Pulsed DC Deposition parameters:

Frequency	350 kHz
Pulse width	1.1 μ s
Power	300 W
Pressure	5×10^{-3} mbar

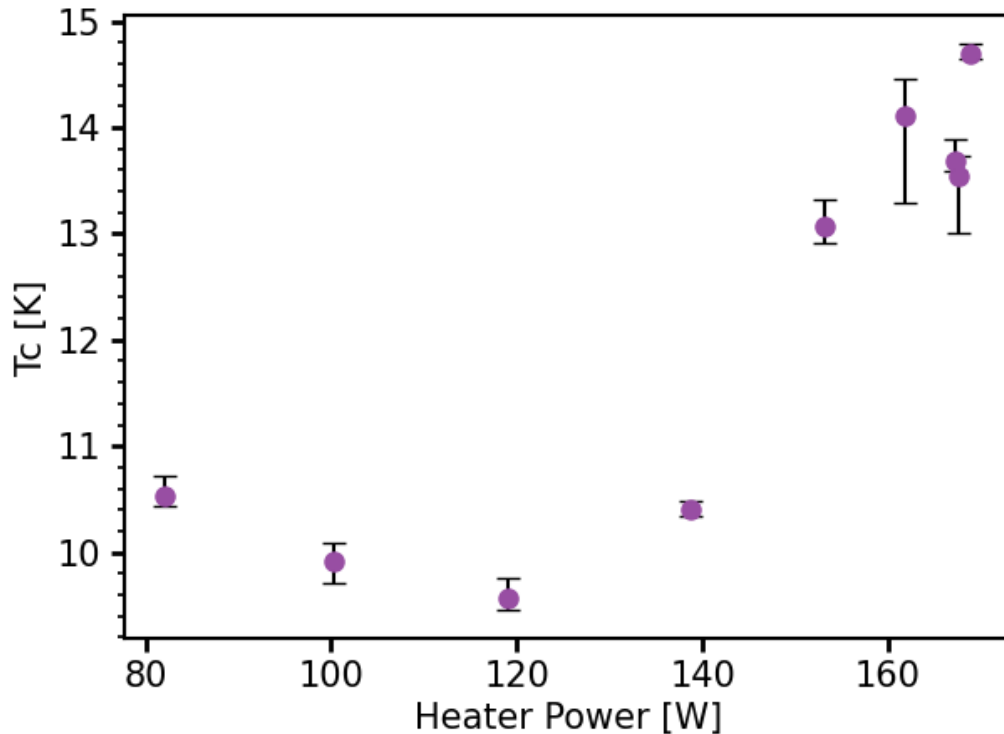
HiPIMS Deposition parameters:

Frequency	1000 Hz
Pulse width	100 μ s
Power	250 W
Duty Cycle	10 %
Pressure	5×10^{-3} mbar



Sample holder and heater stage.

Pulsed DC magnetron sputtering: Sapphire substrates

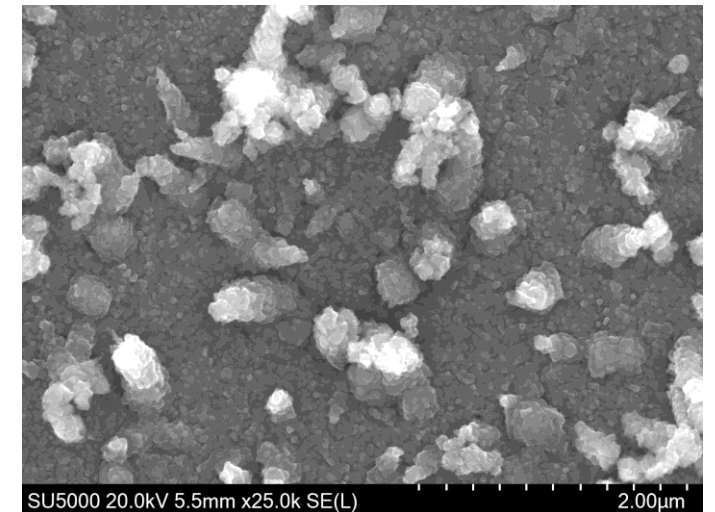
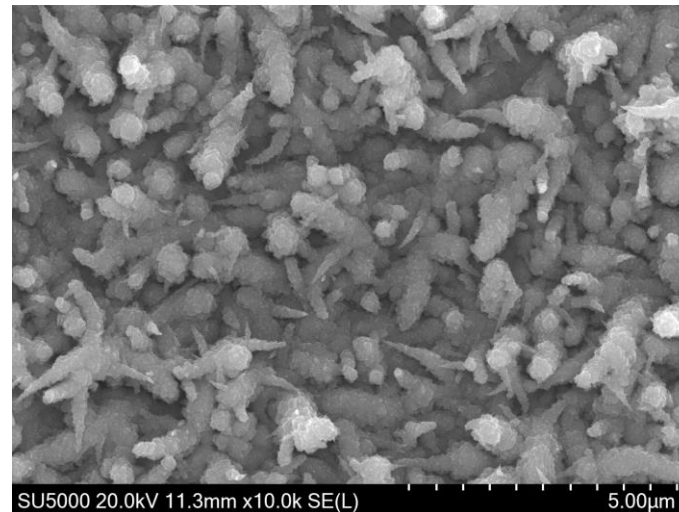


T_c measured by four-point probe [1 mA]

- Max T_c Achieved - $14.69 \text{ K} \pm 0.12 \text{ K}$ at the maximum of the sample heater.

- Inconsistency at higher heater power may be attributed to poor thermal conductivity between sample and holder

- SEM show a preferential 'spiked' and porous film growth unsuitable for SRF applications.



HiPIMS - Sapphire

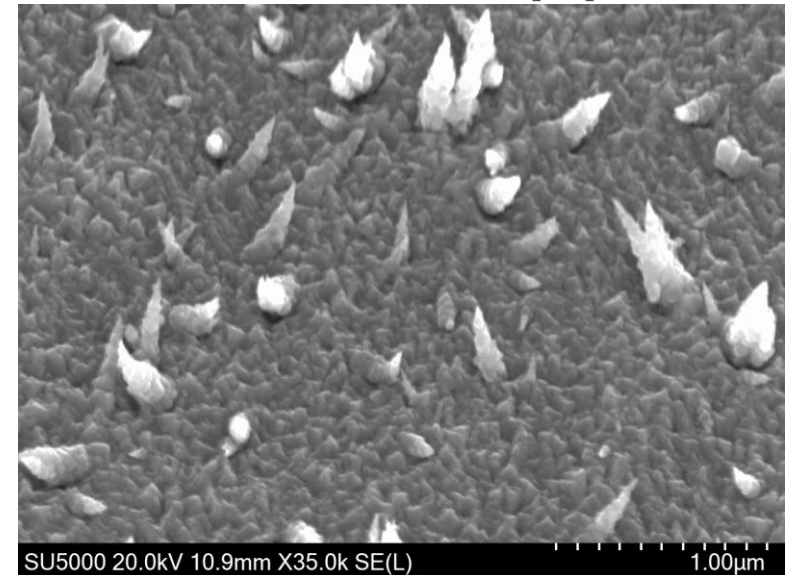
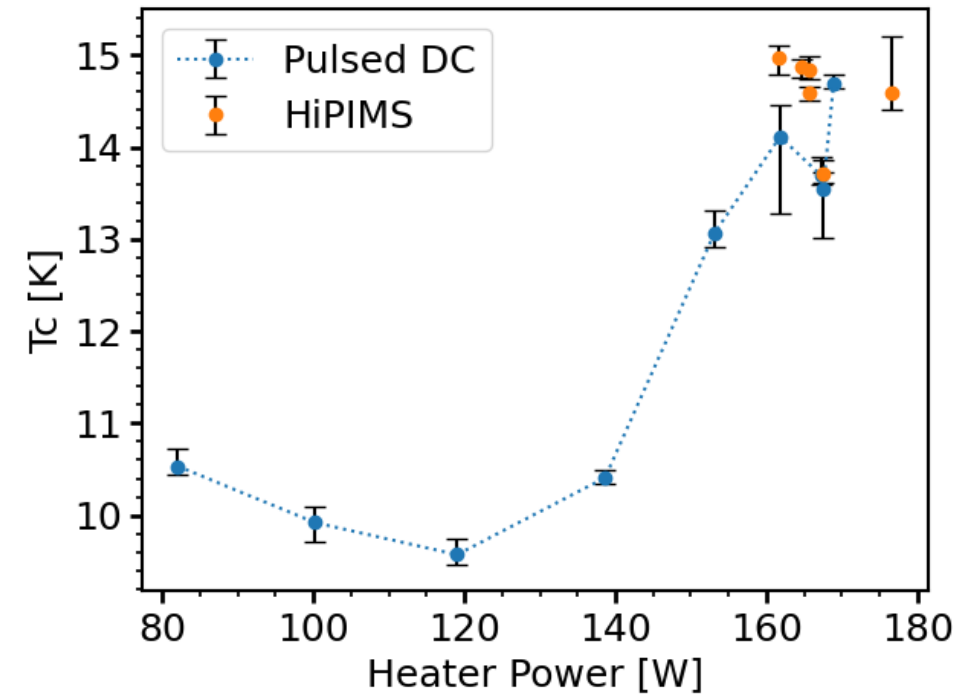
High-power pulsed magnetron sputtering (HiPIMS) was used to improve the density of the films and increase the quality of the films.

Initial study using a duty cycle of 10 % at high temperatures shows improved T_c with smaller ΔT .

Maximum T_c achieved is $14.98 \text{ K} \pm 0.2 \text{ K}$.

The SEM images show an improved film growth.

The ‘spikey’ features are still present but in fewer numbers on the surface of the film. Further work is required to investigate lower duty cycles.

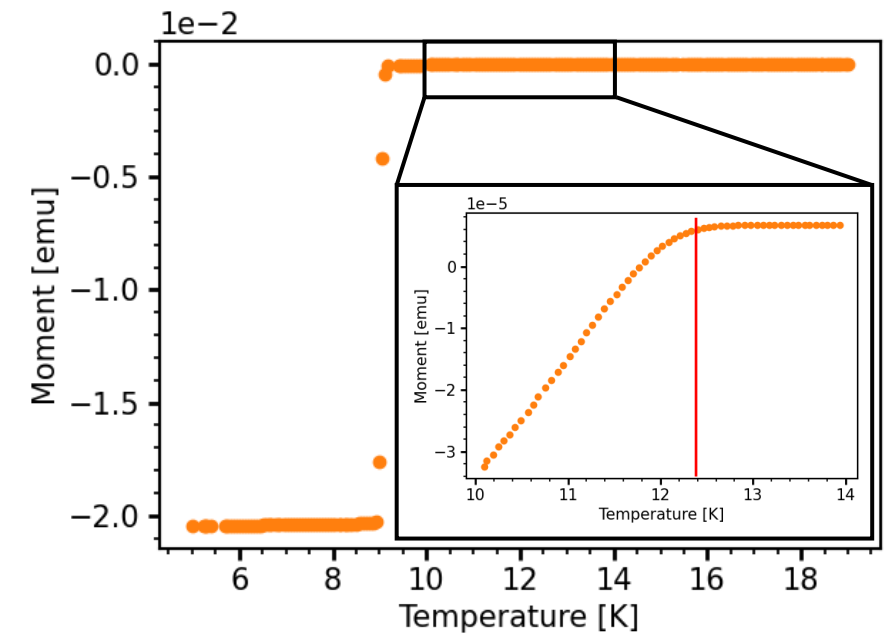
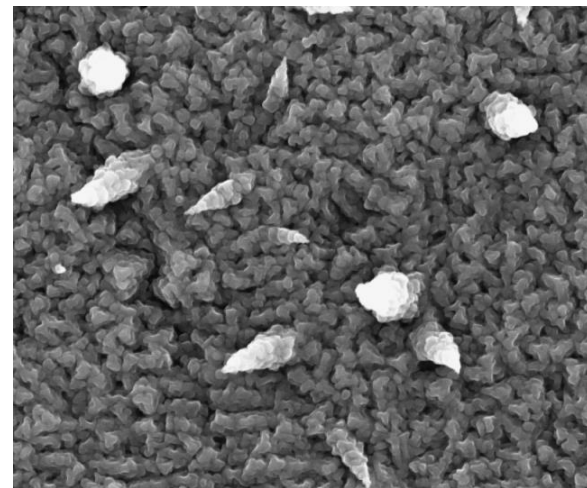
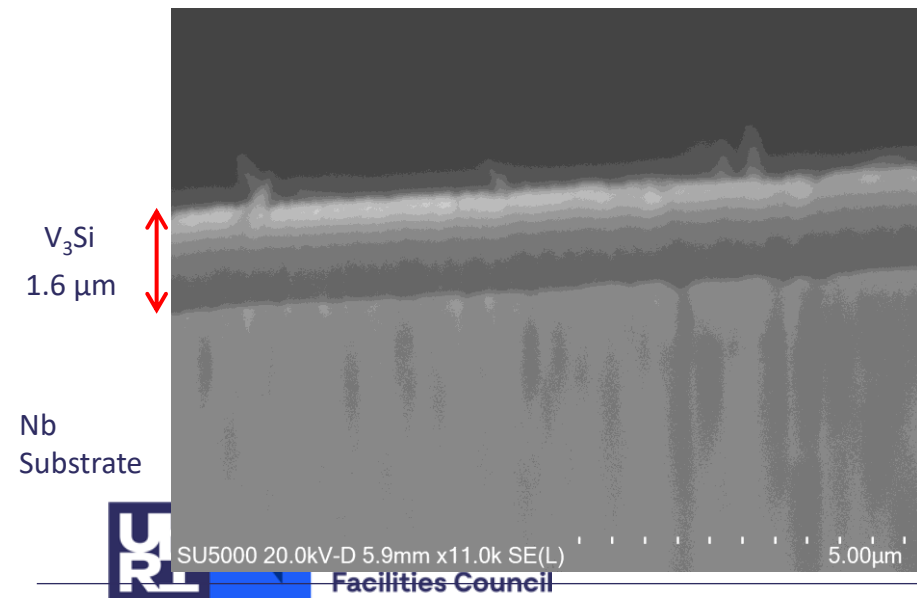


HiPIMS – Polished Nb

V_3Si films were also deposited on polished Nb substrates ($R_{rms} = < 150$ nm). Cu was not chosen due to the high temperatures required for deposition.

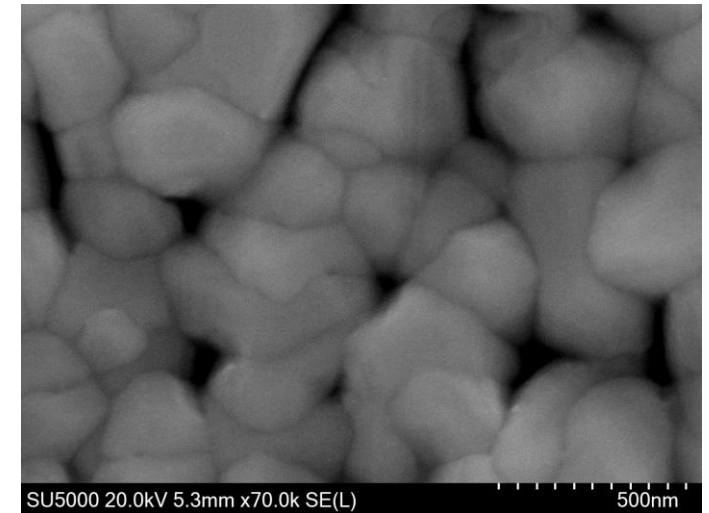
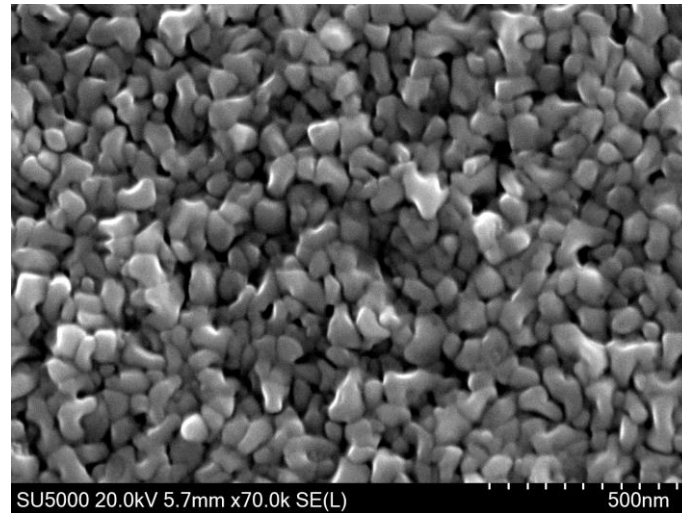
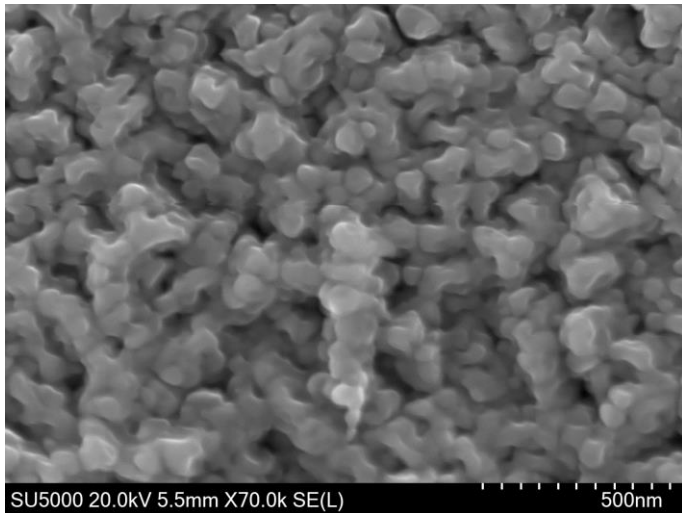
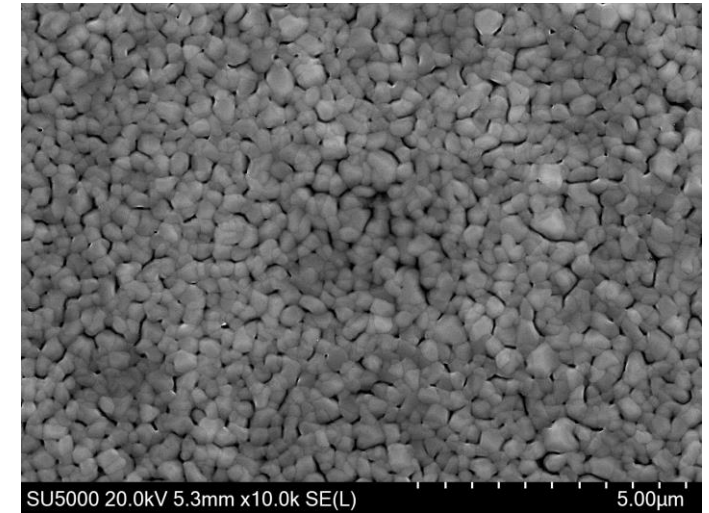
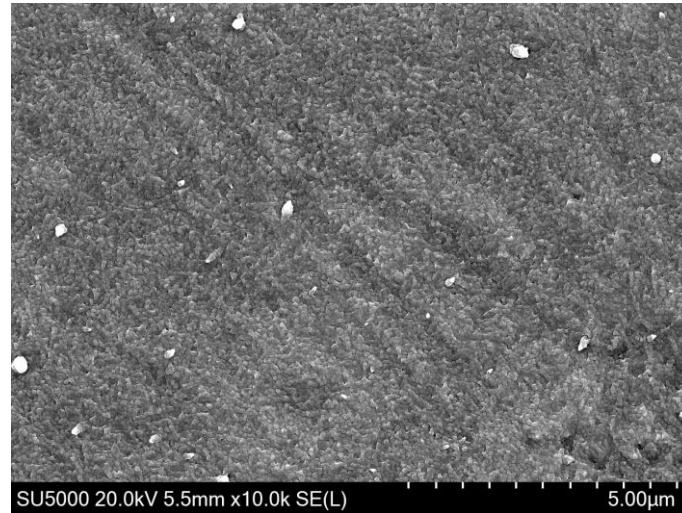
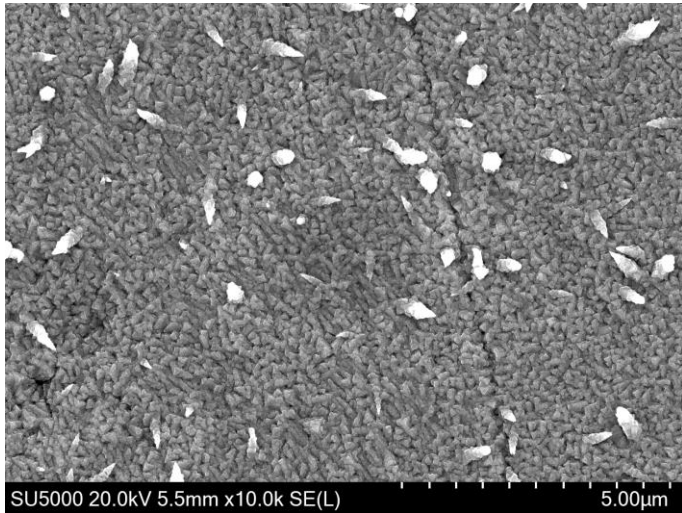
The SEM shows a slightly more open structure compared to the sapphire deposited films. The spiked features are still observed.

SQUID VSM was conducted at RAL, showing a transition at ~ 12.2 K.



T_c measured by SQUID VSM at RAL

HiPIMS and sample bias



-50

-75

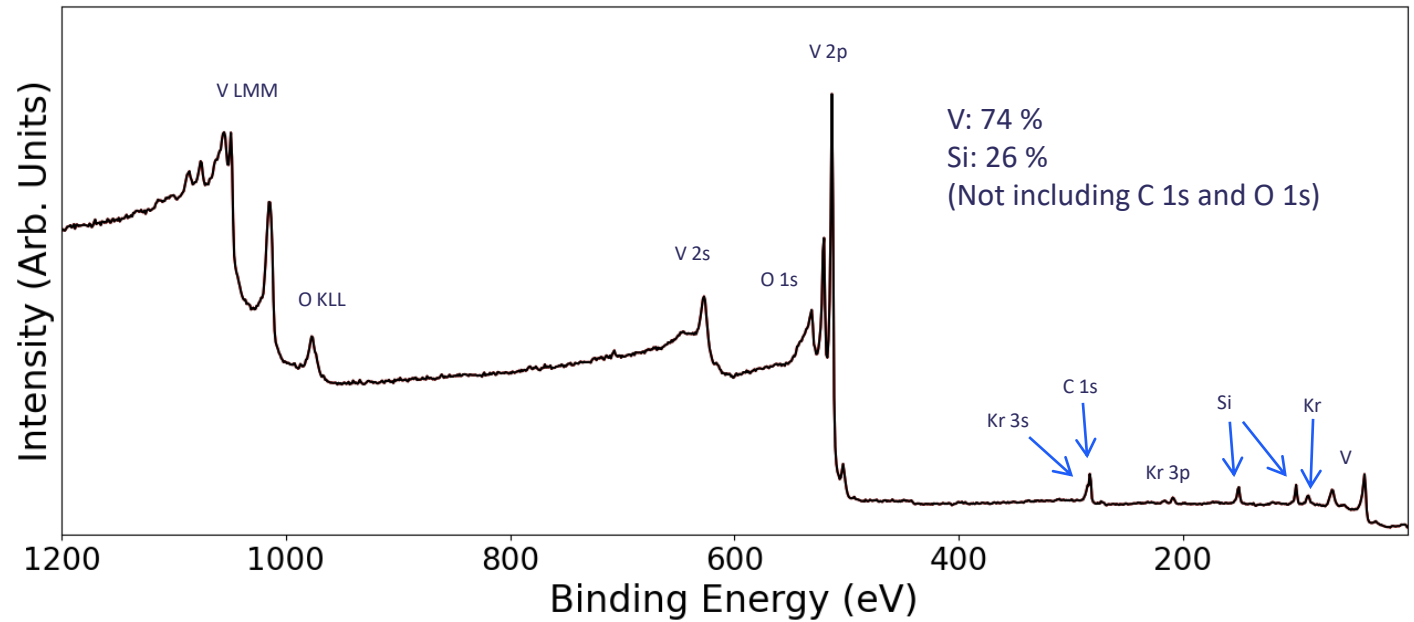
Biased HiPIMS

- SIMS shows a distinct V₃Si film with a consistent level of carbon throughout the film. Oxygen is mostly at the surface but is present in the bulk.

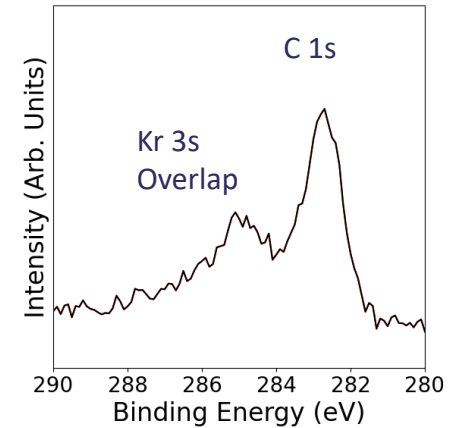
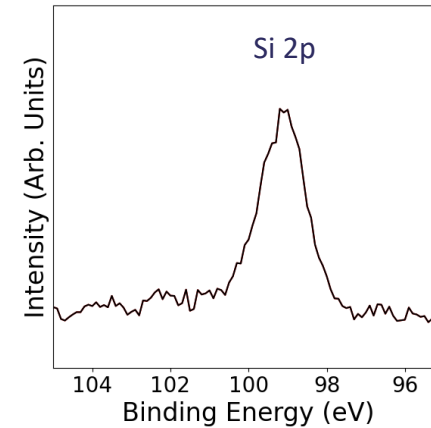
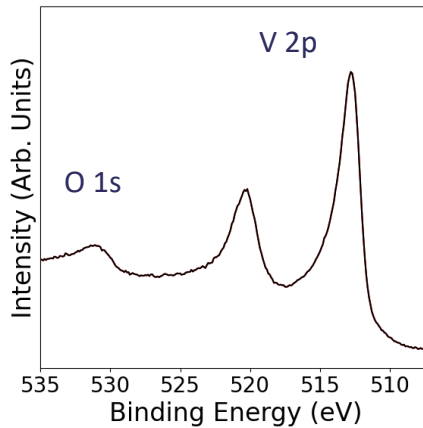
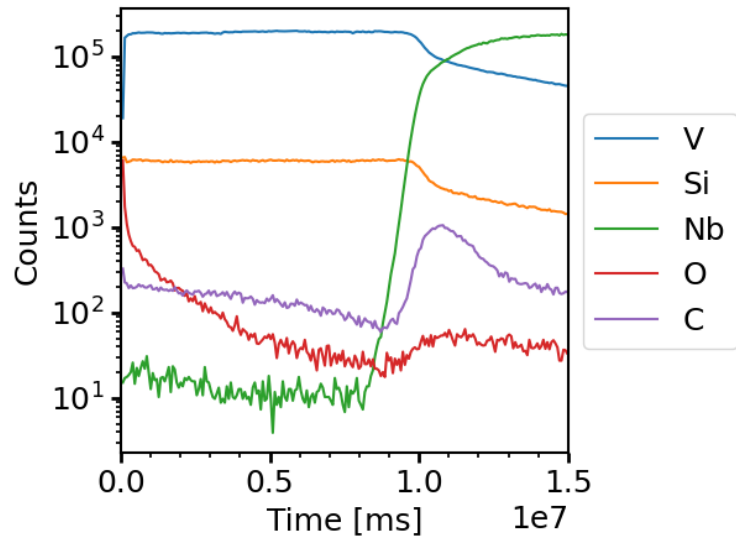
- XPS shows a V:Si ratio of 74 %: 26% and the presence of carbon and oxygen in the bulk of the film agreeing with SIMS.

- Carbon is in a carbide bonding environment suggesting formation during deposition.

XPS after Kr⁺ sputtering *in situ*



SIMS



Summary and Future Work

Significant progress has been made towards V_3Si films for SRF applications.

Further work:

- A study of duty cycle to improve film density and quality.
- Carbon contamination needs to be investigated (target or deposition system?).
- Samples need to be produced for surface resistance measurements and testing.
- Thin film growth on different substrates

Summary (Nb₃Sn)

- Synthesis Nb₃Sn using an alloy target ensure the correct stoichiometry through out the depth of the film.
- The surface of the Nb₃Sn is always terminated by Nb₂O₅, NbO₂ and SnO.
- The surface is also Sn rich and Nb deficient.
- Optimum deposition parameters was stablished for Nb₃Sn on sapphire with T_c very close to bulk value of 18.3 K
- The optimum deposition parameters were:
 - Deposition power 50W DC
 - Deposition temperature 570 C
 - Deposition pressure 5x10⁻³ mbar
- Nb₃Sn can be deposited without any buffer layer on Cu substrate with good adhesion and surface resistance (results from Choke cavity, Dan Seal)
- The observed Cu concentration at the surface is estimated to be about 2 to 3 percent within the 150 nm top surface, the concentration gradually decrease below 1 % through the bulk.
- There is sharp interface between the copper substrate and Nb₃Sn.
- Nb₃Sn deposited on sapphire
- The Cu segregation to the surface does not seems to be the source of lower T_c as compared with Sapphire, no copper contamination was observed for Nb₃Sn deposited on Nb which showed a lower T_c of 16 K.

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